

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A5			Update product family	03/25'26	Frank

**CUSTOMER DRAWING**  
**RoHS Compliant**

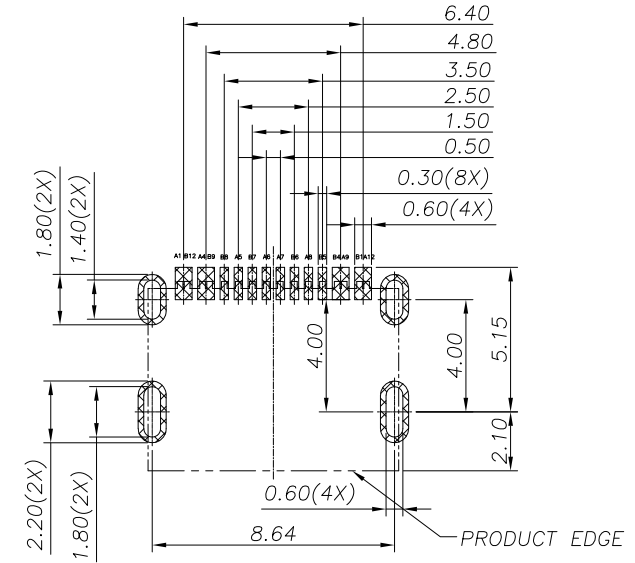
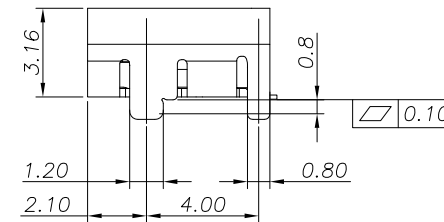
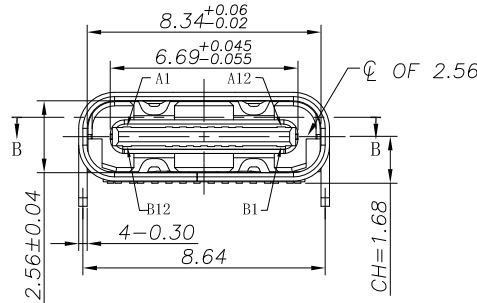
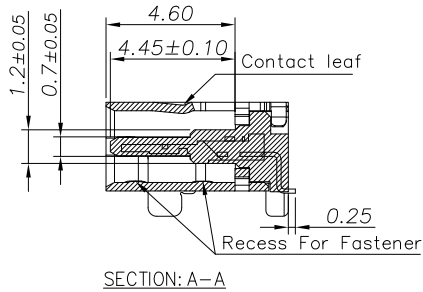
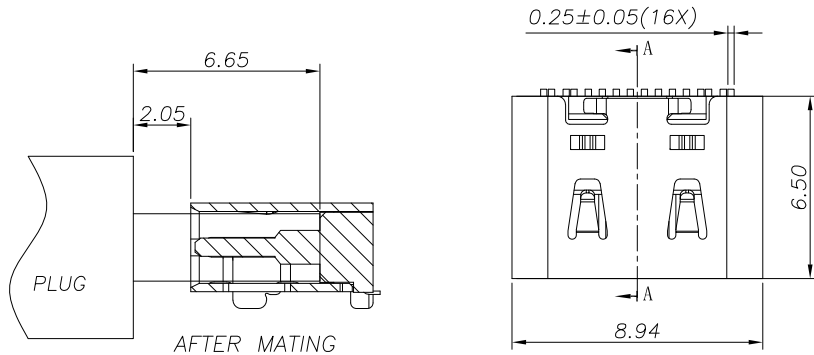
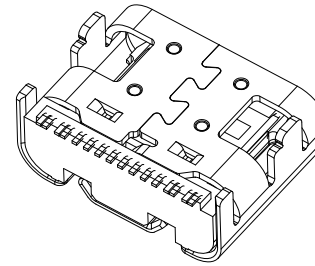
**ORDERING INFORMATION**

**MCCF - R1W1 (XX AT)**

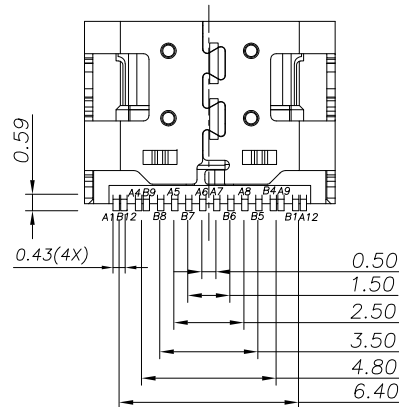
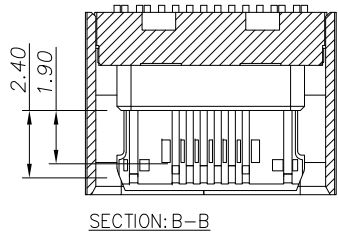
- ① **PRODUCT SERIES:**  
USB C TYPE connector – Receptacle (Female) side.
- ② **ITEM NO.:**  
Right Angle– Single Row SMD 16pin  
On board type/ Body 6.5L

- ③ **GOLD PLATING :**  
See table.

**3D VIEW**



**RECOMMENDED PCB LAYOUT**  
**GENERAL TOLERANCE: ±0.05**



**TABLE:**

MCCF-R1W1(30AT)	CONTACT AREA: GOLD 30u". SOLDER AREA: GOLD FLASH. 50~80u" NICKEL UNDERPLATING OVERALL	30~50u" NICKEL UNDERPLATING OVERALL
MCCF-R1W1(03AT)	CONTACT AREA: GOLD 3u". SOLDER AREA: GOLD FLASH. 50~80u" NICKEL UNDERPLATING OVERALL	30~50u" NICKEL UNDERPLATING OVERALL
MCCF-R1W1(01AT)	CONTACT AREA: G/F. SOLDER AREA: G/F. 50~80u" NICKEL UNDERPLATING OVERALL	30~50u" NICKEL UNDERPLATING OVERALL
PRODUCT P/N	CONTACT PLATED	SHELL PLATED

**NOTES:**

1. MATERIAL:
  - (1) HOUSING: HIGH TEMP PLASTIC, UL94 V-0.
  - (2) CONTACT: COPPER ALLOY, REFER TO THE P/N.
  - (3) MID PLATE: STAINLESS STEEL.
  - (4) SHELL: STAINLESS STEEL.
2. PLATED:
  - (1) CONTACT: Gold over Nickel 50~80u" under-plating.
  - (2) SHELL: 30~50u" Nickel on solder area.
  - (3) MID PLATE: CLEAR ONLY

**PIN ASSIGNMENTS**

PIN NO.	A1	A4	A5	A6	A7	A8	A9	A12
SIGNAL NAME	GND	VBUS	CC1	Dp1	Dn1	SBU1	VBUS	GND
PIN NO.	B12	B9	B8	B7	B6	B5	B4	B1
SIGNAL NAME	GND	VBUS	SBU2	Dn2	Dp2	CC2	VBUS	GND

**SUNFUN**

**SUNFUN TECHNOLOGY LTD**

DRAW NO.	MCCF-R1W1(A5)	DATE	03/25'26	MATERIAL:	SEE NOTES	DRAW NAME:	USB C Type CONN – FEMALE Right Angle– Single Row SMD 16pin On board type/ Body 6.5L
DESIGN:	Frank	03/25'26	FINISH:	SEE NOTES		MODEL:	USB C TYPE CONN
CHECK:	Frank	03/25'26	FILE:	MCCF-R1W1(A5)		UNIT:	mm
REVIEW:	Johnson	03/25'26	P/N:	SEE TABLE		SHEET:	1/1
APPROVED	Johnson	03/25'26	REV. A5	SCALE			

DIM	TOL
X.X	±0.30
X.XX	±0.20
X.XXX	±0.10